



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IAUA250N04S6N008	<b>Issued</b>	15. June 2021
<b>MA#</b>	MA005351827		
<b>Package</b>	PG-HSOF-5-1	<b>Weight*</b>	368.88 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.642	0.45	0.45	4451	4451
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.13	13.14	131256	131426
wire	noble metal	gold	7440-57-5	0.039	0.01	0.01	106	106
encapsulation	inorganic material	zinc oxide	1314-13-2	1.418	0.38		3844	
	miscellaneous	miscellaneous	-	5.671	1.54		15375	
	plastics	epoxy resin	-	21.268	5.77		57655	
	inorganic material	silicon dioxide	60676-86-0	113.427	30.75	38.44	307491	384365
lead finish	non noble metal	tin	7440-31-5	3.673	1.00	1.00	9957	9957
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.043	0.01		117	
	noble metal	silver	7440-22-4	0.054	0.01		147	
	non noble metal	lead	7439-92-1	2.065	0.56	0.58	5598	5862
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		77	
	non noble metal	copper	7440-50-8	28.224	7.65	7.66	76512	76612
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		387	
	non noble metal	copper	7440-50-8	142.638	38.67	38.72	386677	387180
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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